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OpenVPX Faceplates From Pixus are Customizable for Supplemental Air Intake

Waterloo, Ontario — Nov 19, 2019 – Pixus Technologies, a provider of embedded computing and enclosure solutions, offers front faceplate panels for OpenVPX modules with customized cutouts. These hole patterns include designs for airflow intake.

Highly compact OpenVPX systems where the modules are loaded horizontally often have minimal space available for airflow intake in front-to-rear cooling configurations.   To supplement the chassis cooling, it can be beneficial to have air intake holes that allow more airflow to be pulled directly over the OpenVPX modules. With Pixus' custom front panel and chassis design capability, the company can offer an optimized cooling solution for high power and density systems.

The customizable front panels come in 3U and 6U sizes with various widths depending on the solution requirements.

Pixus offers OpenVPX backplanes, chassis platforms, components, and specialty products. The company also provides ruggedization and enclosure customization services.

About Pixus Technologies

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs.   Pixus also has an extensive offering of VME-based and cPCI-based solutions.   In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.